

Title (en)

LIQUID-TIGHT SLIP-CASTING MOLDS AND METHOD FOR PRODUCTION THEREOF

Publication

**EP 0389234 A3 19910502 (EN)**

Application

**EP 90302956 A 19900320**

Priority

JP 3189689 U 19890320

Abstract (en)

[origin: EP0389234A2] A mold (1) for cast-molding a slip under pressure is provided. The mold comprises a divisible casting mold (1) including at least two mold portions (8,9) to form a slip-depositing mold cavity (18) when mated together; a sealing material layer (11) attached onto at least the whole mating filter surface (16) of at least one mold portion to be mated; and a resilient material layer (10) attached onto one of the sealing material layer (11) and another mating filter surface (16), along slip-depositing divisible surfaces (12) of the filter layers (2); whereby the mold portions (8,9) mated together are provided with a resilient liquid-tight zone (14) between the mating filter surfaces (16). The mold is readily produced by coating at least the whole mating filter surfaces (16) of at least one mold portion (8,9) to be mated with a sealing compound; applying a releasing material between the mating mold portions (8,9), mating the mold portions, and hardening the sealing compound to provide a sealing material layer (11); and then bonding a resilient material sheet (10) onto one of the resulting sealing material layer (11) and another mating filter surface(16), along slip-depositing divisible surfaces (12) of the filter layers.

IPC 1-7

**B28B 1/26**

IPC 8 full level

**B28B 1/26** (2006.01); **B28B 7/00** (2006.01)

CPC (source: EP)

**B28B 1/261** (2013.01); **B28B 7/0011** (2013.01)

Citation (search report)

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